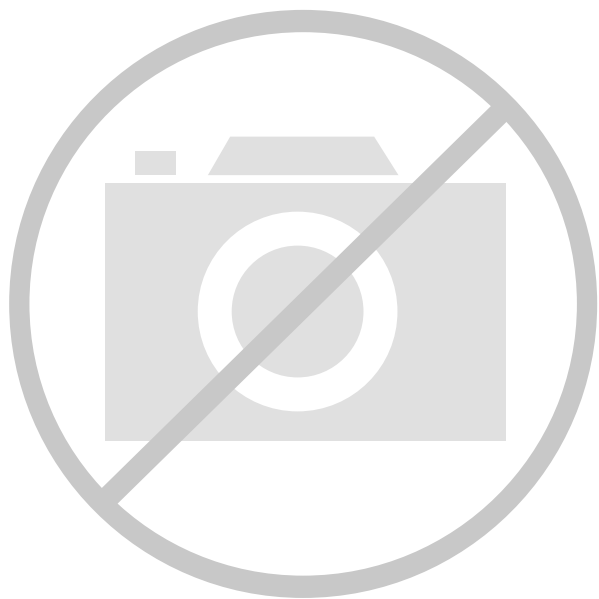




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	2016
Number of Logic Elements/Cells	-
Total RAM Bits	18432
Number of I/O	168
Number of Gates	125000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	324-BGA
Supplier Device Package	324-FBGA (19x19)
Purchase URL	https://www.e-xfl.com/product-detail/microsemi/ax125-fgg324

Table 2-22 • 3.3 V LVTTTL I/O Module

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C (continued)

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
LVTTTL Output Drive Strength = 4 (24mA) / High Slew Rate								
t _{DP}	Input Buffer		1.68		1.92		2.26	ns
t _{PY}	Output Buffer		2.99		3.41		4.01	ns
t _{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		2.49		2.51		2.51	ns
t _{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		2.59		2.95		3.46	ns
t _{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.91		1.93		1.93	ns
t _{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		3.56		4.06		4.77	ns
t _{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t _{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t _{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t _{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t _{HD}	Data Input Hold		0.00		0.00		0.00	ns
t _{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t _{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t _{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t _{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t _{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t _{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t _{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t _{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Timing Characteristics

Table 2-25 • 2.5V LVCMOS I/O Module

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 2.3 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
LVCMOS25 I/O Module Timing								
t _{DP}	Input Buffer		1.95		2.22		2.61	ns
t _{PY}	Output Buffer		3.29		3.74		4.40	ns
t _{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		2.48		2.50		2.51	ns
t _{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		2.48		2.50		2.51	ns
t _{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		5.74		6.54		7.69	ns
t _{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		6.60		7.51		8.83	ns
t _{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t _{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t _{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t _{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t _{HD}	Data Input Hold		0.00		0.00		0.00	ns
t _{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t _{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t _{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t _{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t _{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t _{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t _{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t _{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

1.5 V LVCMOS (JESD8-11)

Low-Voltage Complementary Metal-Oxide Semiconductor for 1.5 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 1.5 V applications. It uses a 3.3 V tolerant CMOS input buffer and a push-pull output buffer.

Table 2-29 • DC Input and Output Levels

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA
-0.3	0.35 VCCI	0.65 VCCI	3.6	0.4	VCCI - 0.4	8 mA	-8 mA

AC Loadings

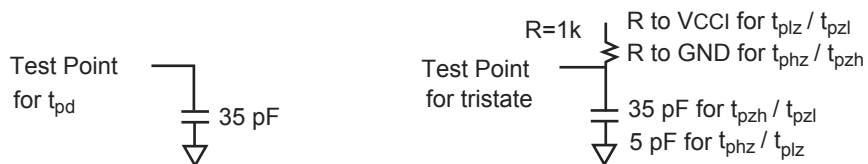


Table 2-30 • AC Test Loads

Table 2-31 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C _{load} (pF)
0	1.5	0.5V _{CCI}	N/A	35

Note: * Measuring Point = VTRIP

Timing Characteristics

Table 2-32 • 1.5V LVCMOS I/O Module

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 1.4 V, TJ = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
LVCMOS15 (JESD8-11) I/O Module Timing								
t _{DP}	Input Buffer		3.59		4.09		4.81	ns
t _{PY}	Output Buffer		6.05		6.89		8.10	ns
t _{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		3.31		3.34		3.34	ns
t _{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		4.56		4.58		4.59	ns
t _{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		6.37		7.25		8.52	ns
t _{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		6.94		7.90		9.29	ns
t _{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t _{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t _{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t _{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t _{HD}	Data Input Hold		0.00		0.00		0.00	ns
t _{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t _{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t _{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t _{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t _{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t _{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t _{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t _{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Table 2-57 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)
1.2 – 0.125	1.2 + 0.125	1.2

Note: * Measuring Point = VTRIP

Timing Characteristics

Table 2-58 • LVDS I/O Module

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 2.3 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		Units
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	
LVDS Output Module Timing								
t _{DP}	Input Buffer	1.80		2.05		2.41		ns
t _{PY}	Output Buffer	2.32		2.64		3.11		ns
t _{CLKQ}	Clock-to-Q for the I/O input register	0.67		0.77		0.90		ns
t _{OCLKQ}	Clock-to-Q for the I/O output register and the I/O enable register	0.67		0.77		0.90		ns
t _{SUD}	Data Input Set-Up	0.23		0.27		0.31		ns
t _{SUE}	Enable Input Set-Up	0.26		0.30		0.35		ns
t _{HD}	Data Input Hold	0.00		0.00		0.00		ns
t _{HE}	Enable Input Hold	0.00		0.00		0.00		ns
t _{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t _{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t _{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t _{REASYN}	Asynchronous Recovery Time	0.13		0.15		0.17		ns
t _{HASYN}	Asynchronous Removal Time	0.00		0.00		0.00		ns
t _{CLR}	Asynchronous Clear-to-Q	0.23		0.27		0.31		ns
t _{PRESET}	Asynchronous Preset-to-Q	0.23		0.27		0.31		ns

Module Specifications

C-Cell

Introduction

The C-cell is one of the two logic module types in the AX architecture. It is the combinatorial logic resource in the Axcelerator device. The AX architecture implements a new combinatorial cell that is an extension of the C-cell implemented in the SX-A family. The main enhancement of the new C-cell is the addition of carry-chain logic.

The C-cell can be used in a carry-chain mode to construct arithmetic functions. If carry-chain logic is not required, it can be disabled.

The C-cell features the following (Figure 2-27):

- Eight-input MUX (data: D0-D3, select: A0, A1, B0, B1). User signals can be routed to any one of these inputs. Any of the C-cell inputs (D0-D3, A0, A1, B0, B1) can be tied to one of the four routed clocks (CLKE/F/G/H).
- Inverter (DB input) can be used to drive a complement signal of any of the inputs to the C-cell.
- A carry input and a carry output. The carry input signal of the C-cell is the carry output from the C-cell directly to the north.
- Carry connect for carry-chain logic with a signal propagation time of less than 0.1 ns.
- A hardwired connection (direct connect) to the adjacent R-cell (Register Cell) for all C-cells on the east side of a SuperCluster with a signal propagation time of less than 0.1 ns.

This layout of the C-cell (and the C-cell Cluster) enables the implementation of over 4,000 functions of up to five bits. For example, two C-cells can be used together to implement a four-input XOR function in a single cell delay.

The carry-chain configuration is handled automatically for the user with Microsemi's extensive macro library (please see the *Antifuse Macro Library Guide* for a complete listing of available Axcelerator macros).

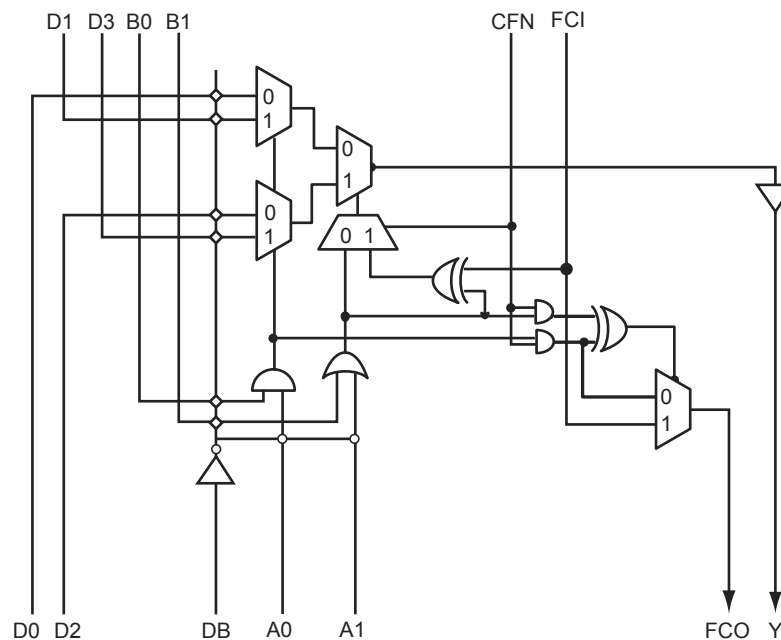


Figure 2-27 • C-Cell

Implementation Example:

Figure 2-47 shows a complex clock distribution example. The reference clock (RefCLK) of PLLE is being sourced from non-clock signal pins (INBUF to PLLINT). The CLK1 output of PLLE is being fed to the RefCLK input of PLLF. The CLK2 output of PLLE is driving logic (via PLLOUT). In turn, this logic is driving the global resource CLKE. PLLF is driving both CLKF and CLKG global resources.

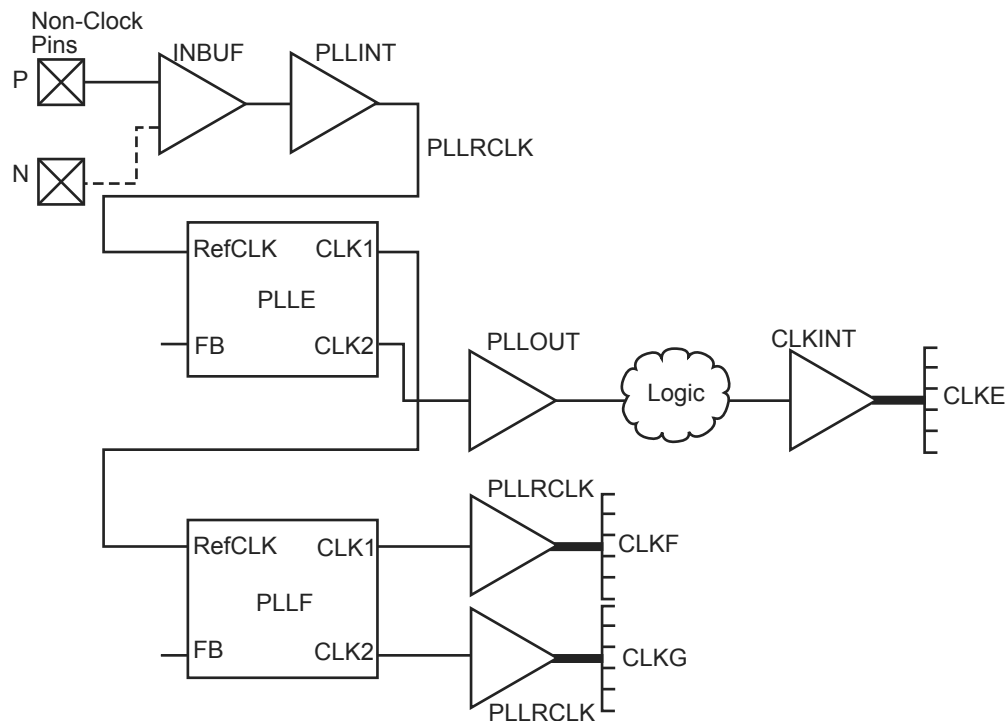


Figure 2-47 • Complex Clock Distribution Example

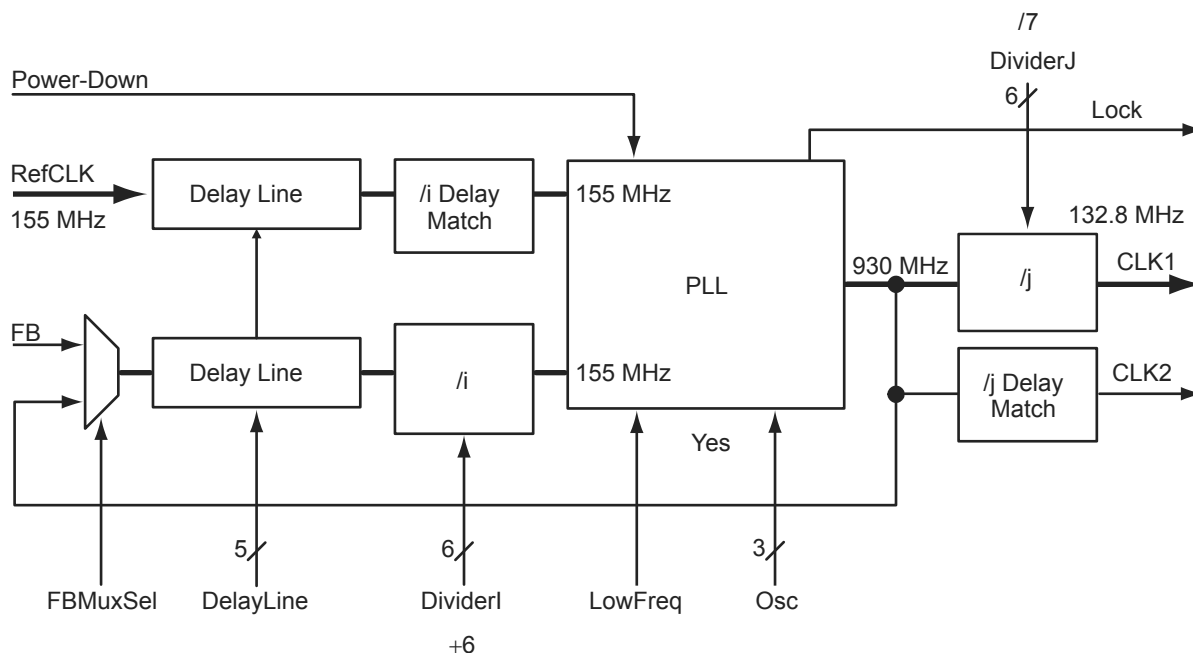


Figure 2-54 • Using the PLL 155 MHz In, 133 MHz Out

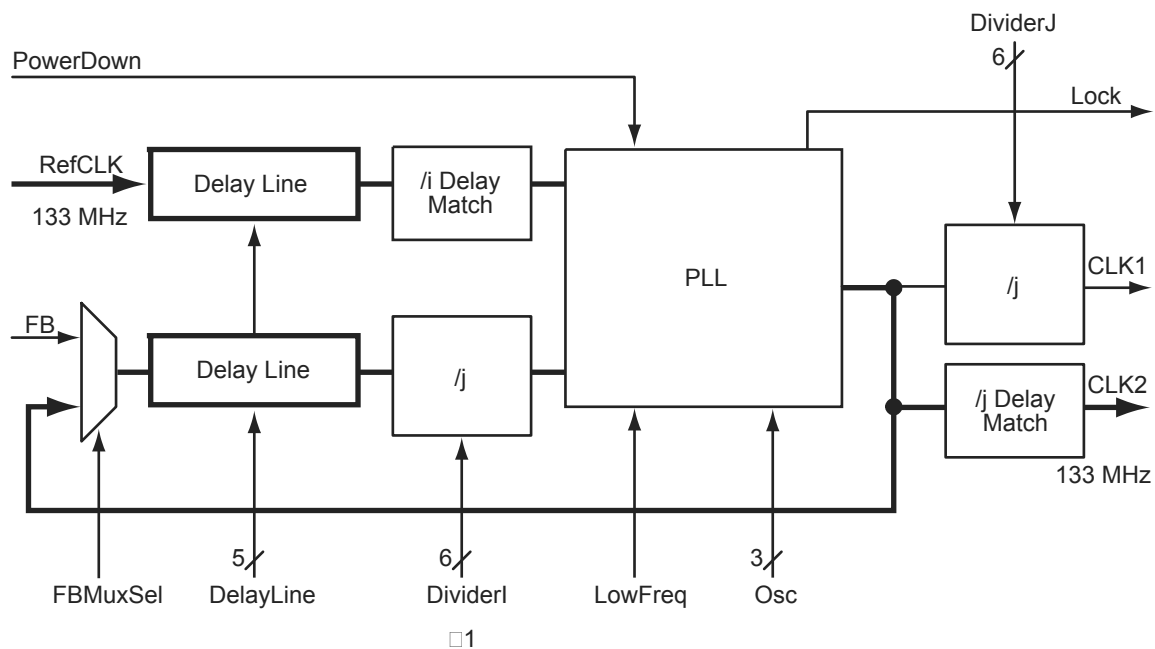


Figure 2-55 • Using the PLL Delaying the Reference Clock

Clock Skew Minimization

Figure 2-56 indicates how feedback from the clock network can be used to create minimal skew between the distributed clock network and the input clock. The input clock is fed to the reference clock input of the PLL. The output clock (CLK2) feeds a routed clock network. The feedback input to the PLL uses a clock input delayed by a routing network. The PLL then adjusts the phase of the input clock to match the delayed clock, thus providing nearly zero effective skew between the two clocks. Refer to the *Axcelerator Family PLL and Clock Management* application note for more information.

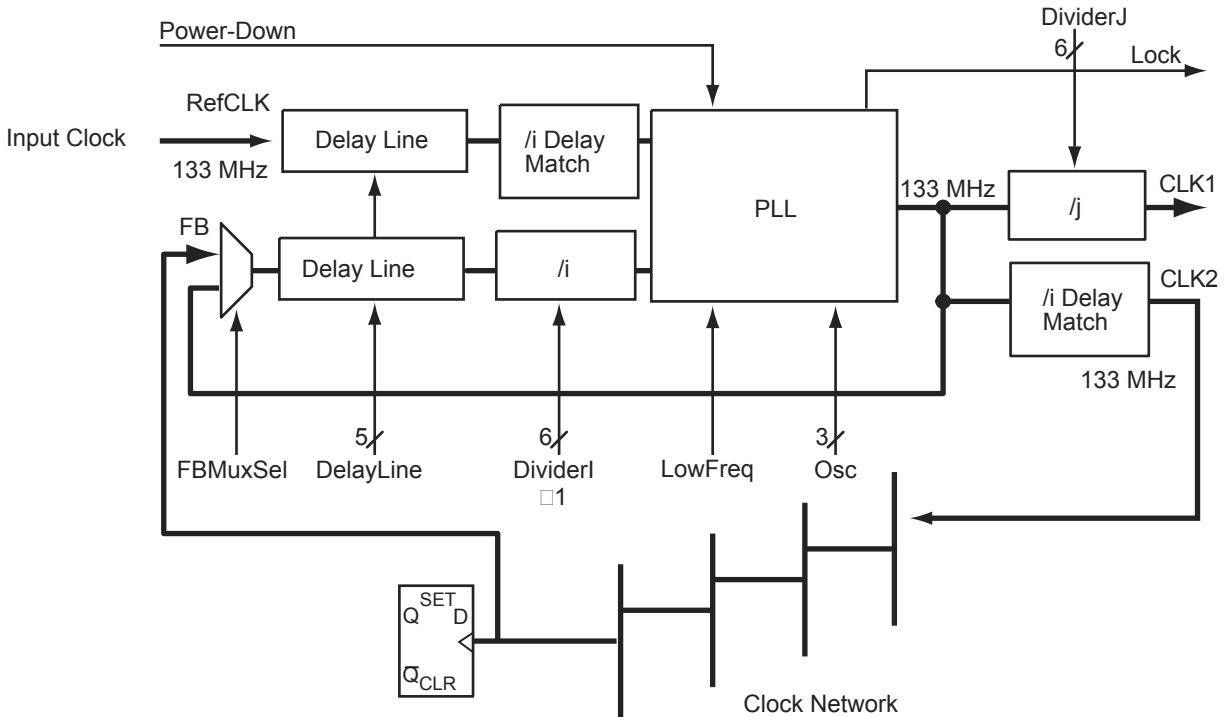


Figure 2-56 • Using the PLL for Clock Deskewing

RAM

Each memory block consists of 4,608 bits that can be organized as 128x36, 256x18, 512x9, 1kx4, 2kx2, or 4kx1 and are cascadable to create larger memory sizes. This allows built-in bus width conversion (Table 2-86). Each block has independent read and write ports which enable simultaneous read and write operations.

Table 2-86 • Memory Block WxD Options

Data-word (in bits)	Depth	Address Bus	Data Bus
1	4,096	RA/WA[11:0]	RD/WD[0]
2	2,048	RA/WA[10:0]	RD/WD[1:0]
4	1,024	RA/WA[9:0]	RD/WD[3:0]
9	512	RA/WA[8:0]	RD/WD[8:0]
18	256	RA/WA[7:0]	RD/WD[17:0]
36	128	RA/WA[6:0]	RD/WD[35:0]

Clocks

The RCLK and the WCLK have independent source polarity selection and can be sourced by any global or local signal.

RAM Configurations

The AX architecture allows the read side and write side of RAMs to be organized independently, allowing for bus conversion. For example, the write side can be set to 256x18 and the read side to 512x9.

Both the write width and read width for the RAM blocks can be specified independently and changed dynamically with the WW (write width) and RW (read width) pins. The D x W different configurations are: 128 x 36, 256 x 18, 512 x 9, 1k x 4, 2k x 2, and 4k x 1. The allowable RW and WW values are shown in Table 2-87.

Table 2-87 • Allowable RW and WW Values

RW(2:0)	WW(2:0)	D x W
000	000	4k x 1
001	001	2k x 2
010	010	1k x 4
011	011	512 x 9
100	100	256 x 18
101	101	128 x 36
11x	11x	reserved

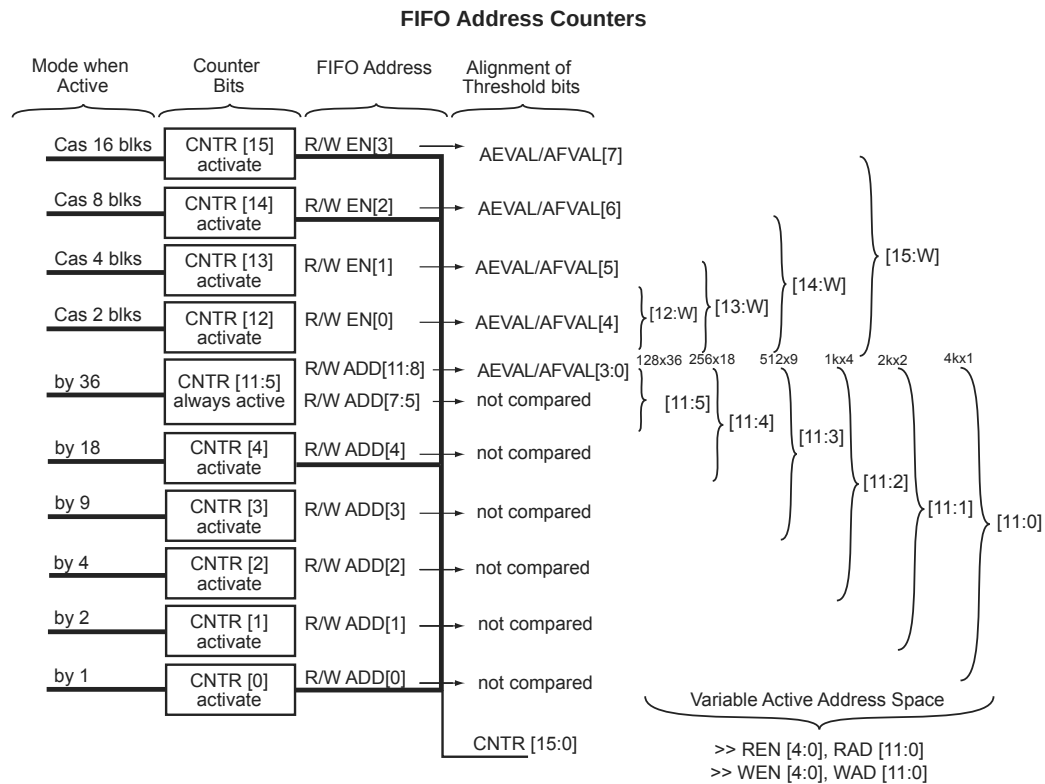
When widths of one, two, and four are selected, the ninth bit is unused. For example, when writing nine-bit values and reading four-bit values, only the first four bits and the second four bits of each nine-bit value are addressable for read operations. The ninth bit is not accessible. Conversely, when writing four-bit values and reading nine-bit values, the ninth bit of a read operation will be undefined.

FIFO Flag Logic

The FIFO is user configurable into various DEPTHS and WIDTHS. Figure 2-62 shows the FIFO address counter details.

- Bits 11 to 5 are active for all modes.
- As the data word size is reduced, more least-significant bits are added to the address.
- As the number of cascaded blocks increases, the number of significant bits in the address increases.

For example, if four blocks are cascaded as a 1kx16 FIFO with each block having a 1kx4 aspect ratio, bits 11 to 2 of the address will be used to specify locations within each RAM block, whereas bits 13 and 12 will be used to specify the RAM block.



Note: Inactive counter bits are set to zero.

Figure 2-62 • FIFO Address Counters

The AFULL and AEMPTY flag threshold values are programmable. The threshold values are AFVAL and AEVAL, respectively. Although the trigger threshold for each flag is defined with eight bits, the effective number of threshold bits in the comparison depends on the configuration. The effective number of threshold bits corresponds to the range of active bits in the FIFO address space (Table 2-94).

Table 2-94 • FIFO Flag Logic

Mode	Inactive AEVAL/AFVAL Bits	Inactive DIFF Bits (set to 0)	DIFF Comparison to AFVAL/AEVAL
Non-cascade	[7:4]	[15:12]	DIFF[11:8] with AE/FVAL[3:0]
Cascade 2 blocks	[7:5]	[15:13]	DIFF[12:8] with AE/FVAL[4:0]
Cascade 4 blocks	[7:6]	[15:14]	DIFF[13:8] with AE/FVAL[5:0]
Cascade 8 blocks	[7]	[15]	DIFF[14:8] with AE/FVAL[6:0]
Cascade 16 blocks	None	None	DIFF[15:8] with AE/FVAL[7:0]

Programming

Device programming is supported through the Silicon Sculptor II, a single-site, robust and compact device programmer for the PC. Up to four Silicon Sculptor IIs can be daisy-chained and controlled from a single PC host. With standalone software for the PC, Silicon Sculptor II is designed to allow concurrent programming of multiple units from the same PC when daisy-chained.

Silicon Sculptor II programs devices independently to achieve the fastest programming times possible. Each fuse is verified by Silicon Sculptor II to ensure correct programming. Furthermore, at the end of programming, there are integrity tests that are run to ensure that programming was completed properly. Not only does it test programmed and nonprogrammed fuses, Silicon Sculptor II also provides a self-test to test its own hardware extensively.

Programming an Axcelerator device using Silicon Sculptor II is similar to programming any other antifuse device. The procedure is as follows:

1. Load the *.AFM file.
2. Select the device to be programmed.
3. Begin programming.

When the design is ready to go to production, Microsemi offers device volume-programming services either through distribution partners or via our In-House Programming Center.

In addition, BP Microsystems offers multi-site programmers that provide qualified support for Axcelerator devices.

For more details on programming the Axcelerator devices, please refer to the *Silicon Sculptor II User's Guide*.

FG484	
AX500 Function	Pin Number
Bank 0	
IO00NB0F0	E3
IO00PB0F0	D3
IO01NB0F0	E7
IO01PB0F0	E6
IO02NB0F0	C5
IO02PB0F0	C4
IO03NB0F0	D7
IO03PB0F0	D6
IO04NB0F0	B5
IO04PB0F0	B4
IO05NB0F0	C7
IO05PB0F0	C6
IO06NB0F0	A5
IO06PB0F0	A4
IO07NB0F0	A7
IO07PB0F0	A6
IO08NB0F0	B7
IO08PB0F0	B6
IO10NB0F0	B9
IO10PB0F0	B8
IO11NB0F0	E9
IO11PB0F0	E8
IO12NB0F1	D9
IO12PB0F1	D8
IO13NB0F1	C9
IO13PB0F1	C8
IO14NB0F1	A9
IO14PB0F1	A8
IO15NB0F1	B10
IO15PB0F1	A10
IO16NB0F1	B12
IO16PB0F1	B11
IO18NB0F1	C13
IO18PB0F1	C12

FG484	
AX500 Function	Pin Number
IO19NB0F1/HCLKAN	E11
IO19PB0F1/HCLKAP	E10
IO20NB0F1/HCLKBN	D12
IO20PB0F1/HCLKBP	D11
Bank 1	
IO21NB1F2/HCLKCN	F13
IO21PB1F2/HCLKCP	F12
IO22NB1F2/HCLKDN	E14
IO22PB1F2/HCLKDP	E13
IO24NB1F2	A14
IO24PB1F2	A13
IO25NB1F2	B14
IO25PB1F2	B13
IO26NB1F2	C15
IO27NB1F2	A16
IO27PB1F2	A15
IO28NB1F2	B16
IO28PB1F2	B15
IO29NB1F2	D16
IO29PB1F2	D15
IO30NB1F2	A18
IO30PB1F2	A17
IO31NB1F2	F15
IO31PB1F2	F14
IO32NB1F3	C17
IO32PB1F3	C16
IO33NB1F3	E16
IO33PB1F3	E15
IO34NB1F3	B18
IO34PB1F3	B17
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IO36NB1F3	C19
IO36PB1F3	C18
IO37NB1F3	F18

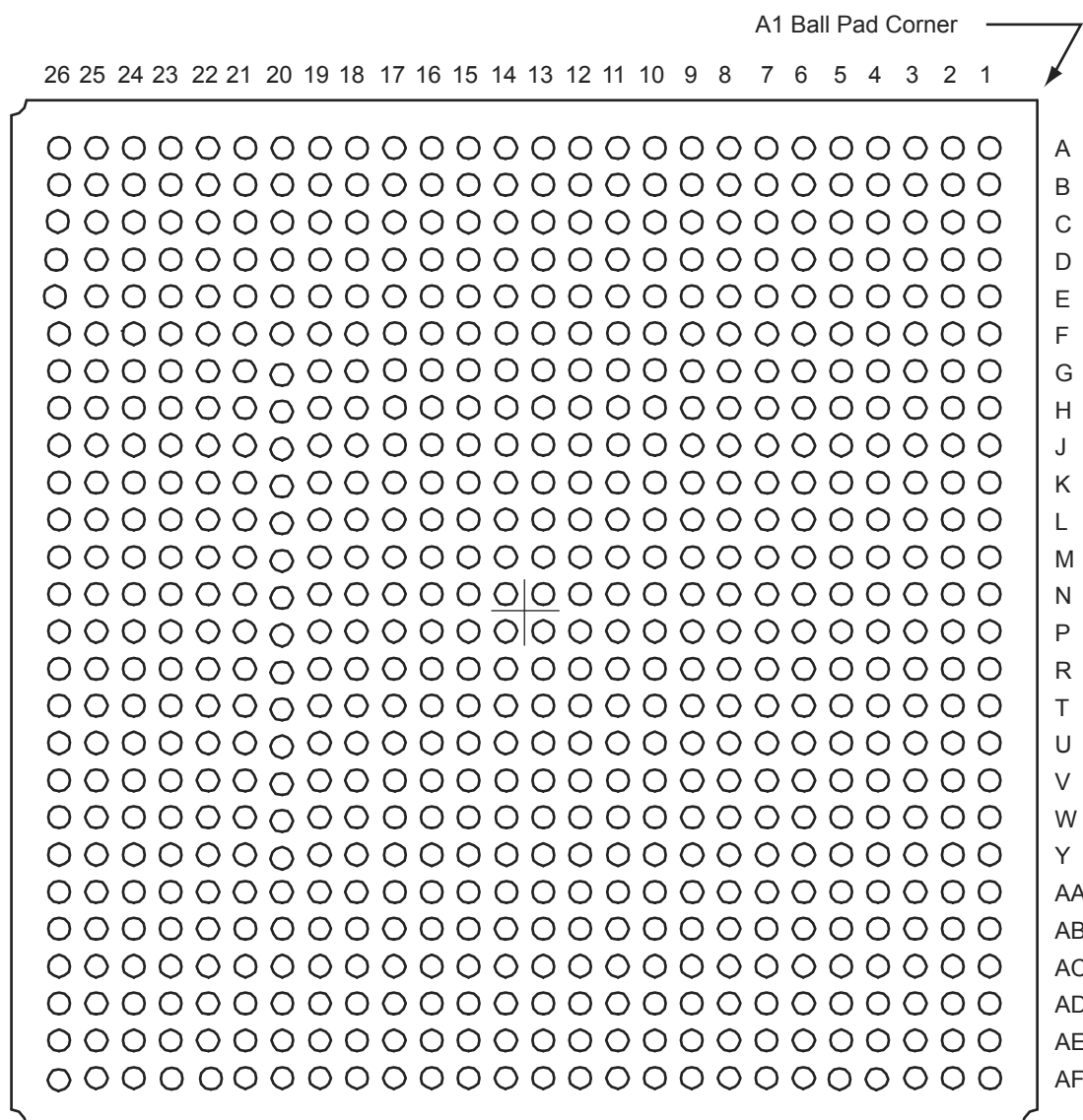
FG484	
AX500 Function	Pin Number
IO37PB1F3	F17
IO38NB1F3	D18
IO38PB1F3	E17
IO39NB1F3	E21
IO39PB1F3	D21
IO40NB1F3	E20
IO40PB1F3	D20
IO41NB1F3	G16
IO41PB1F3	G15
Bank 2	
IO42NB2F4	F19
IO42PB2F4	E19
IO43NB2F4	J16
IO43PB2F4	H16
IO44NB2F4	E22
IO44PB2F4	D22
IO45NB2F4	H19
IO45PB2F4	G19
IO46NB2F4	G22
IO46PB2F4	F22
IO47NB2F4	J17
IO47PB2F4	H17
IO48NB2F4	G20
IO48PB2F4	F20
IO49NB2F4	J18
IO49PB2F4	H18
IO50NB2F4	G21
IO50PB2F4	F21
IO51NB2F4	K19
IO51PB2F4	J19
IO52NB2F5	J21
IO52PB2F5	H21
IO53NB2F5	J20
IO53PB2F5	H20
IO54NB2F5	J22

FG484	
AX500 Function	Pin Number
IO54PB2F5	H22
IO55NB2F5	L17
IO55PB2F5	K17
IO56NB2F5	K21
IO56PB2F5	K22
IO58NB2F5	L20
IO58PB2F5	K20
IO59NB2F5	L18
IO59PB2F5	K18
IO60NB2F5	M21
IO60PB2F5	L21
IO61NB2F5	L16
IO61PB2F5	K16
IO62NB2F5	M19
IO62PB2F5	L19
Bank 3	
IO63NB3F6	N16
IO63PB3F6	M16
IO64NB3F6	P22
IO64PB3F6	N22
IO65NB3F6	N20
IO65PB3F6	M20
IO66NB3F6	P21
IO66PB3F6	N21
IO67NB3F6	N18
IO67PB3F6	N19
IO68NB3F6	T22
IO68PB3F6	R22
IO69NB3F6	N17
IO69PB3F6	M17
IO70NB3F6	T21
IO70PB3F6	R21
IO71NB3F6	P18
IO71PB3F6	P19
IO72NB3F6	R20

FG484	
AX500 Function	Pin Number
IO72PB3F6	P20
IO73PB3F6	R19
IO74NB3F7	V21
IO74PB3F7	U21
IO75NB3F7	V22
IO75PB3F7	U22
IO76NB3F7	U20
IO76PB3F7	T20
IO77NB3F7	R17
IO77PB3F7	P17
IO78NB3F7	W21
IO78PB3F7	W22
IO79NB3F7	T18
IO79PB3F7	R18
IO80NB3F7	W20
IO80PB3F7	V20
IO81NB3F7	U19
IO81PB3F7	T19
IO82NB3F7	U18
IO82PB3F7	V19
IO83NB3F7	R16
IO83PB3F7	P16
Bank 4	
IO84NB4F8	AB18
IO84PB4F8	AB19
IO85NB4F8	T15
IO85PB4F8	T16
IO86NB4F8	AA18
IO86PB4F8	AA19
IO87NB4F8	W17
IO87PB4F8	V17
IO88NB4F8	Y19
IO88PB4F8	W18
IO89NB4F8	U14
IO89PB4F8	U15

FG484	
AX500 Function	Pin Number
IO90NB4F8	Y17
IO90PB4F8	Y18
IO91NB4F8	V15
IO91PB4F8	V16
IO92PB4F8	AB17
IO93NB4F8	Y15
IO93PB4F8	Y16
IO94NB4F9	AA16
IO94PB4F9	AA17
IO95NB4F9	AB14
IO95PB4F9	AB15
IO96NB4F9	W15
IO96PB4F9	W16
IO97NB4F9	AA13
IO97PB4F9	AB13
IO98NB4F9	AA14
IO98PB4F9	AA15
IO100NB4F9	Y14
IO100PB4F9	W14
IO101NB4F9	Y12
IO101PB4F9	Y13
IO102NB4F9	AA11
IO102PB4F9	AA12
IO103NB4F9/CLKEN	V12
IO103PB4F9/CLKEP	V13
IO104NB4F9/CLKFN	W11
IO104PB4F9/CLKFP	W12
Bank 5	
IO105NB5F10/CLKGN	U10
IO105PB5F10/CLKGP	U11
IO106NB5F10/CLKHN	V9
IO106PB5F10/CLKHP	V10
IO107NB5F10	Y10
IO107PB5F10	Y11
IO108NB5F10	AA9

FG676



Note

For Package Manufacturing and Environmental information, visit Resource center at <http://www.microsemi.com/soc/products/rescenter/package/index.html>.

FG676	
AX500 Function	Pin Number
GND	R10
GND	R11
GND	R12
GND	R13
GND	R14
GND	R15
GND	R16
GND	R17
GND	T10
GND	T11
GND	T12
GND	T13
GND	T14
GND	T15
GND	T16
GND	T17
GND	U10
GND	U11
GND	U12
GND	U13
GND	U14
GND	U15
GND	U16
GND	U17
GND	V18
GND	V9
GND	W1
GND	W19
GND	W26
GND	W8
GND	Y20
GND	Y7
GND/LP	C2
NC	A11
NC	A21

FG676	
AX500 Function	Pin Number
NC	A22
NC	A24
NC	A25
NC	AA11
NC	AA19
NC	AA20
NC	AA4
NC	AA5
NC	AA6
NC	AA7
NC	AA8
NC	AA9
NC	AB1
NC	AB11
NC	AB17
NC	AB18
NC	AB19
NC	AB20
NC	AB8
NC	AB9
NC	AC1
NC	AC13
NC	AC14
NC	AC25
NC	AD1
NC	AD11
NC	AD16
NC	AD25
NC	AE1
NC	AF2
NC	AF25
NC	B11
NC	B24
NC	B4
NC	C16

FG676	
AX500 Function	Pin Number
NC	C4
NC	D1
NC	D13
NC	D14
NC	D17
NC	D18
NC	D2
NC	D26
NC	D3
NC	D9
NC	E1
NC	E18
NC	E23
NC	E24
NC	E26
NC	E3
NC	E4
NC	E9
NC	F1
NC	F18
NC	F20
NC	F21
NC	F22
NC	F23
NC	F24
NC	F4
NC	F6
NC	F7
NC	G21
NC	G22
NC	H21
NC	H22
NC	H23
NC	H5
NC	H6

FG896	
AX1000 Function	Pin Number
IO206PB6F19	AB4
IO207NB6F19	W6
IO207PB6F19	W7
IO208NB6F19	AB3
IO208PB6F19	AC3
IO209NB6F19	V8
IO209PB6F19	V9
IO210NB6F19	AA2
IO210PB6F19	AA1
IO211NB6F19	V5
IO211PB6F19	W5
IO212NB6F19	Y3
IO212PB6F19	Y4
IO213NB6F19	V7
IO213PB6F19	V6
IO214NB6F20	W3
IO214PB6F20	W4
IO215NB6F20	U8
IO215PB6F20	U9
IO216NB6F20	W1
IO216PB6F20	W2
IO217NB6F20	U7
IO217PB6F20	U6
IO218NB6F20	U4
IO218PB6F20	V4
IO219NB6F20	T5
IO219PB6F20	U5
IO220NB6F20	U3
IO220PB6F20	V3
IO221NB6F20	T8
IO221PB6F20	T9
IO222NB6F20	U2
IO222PB6F20	V2
IO223NB6F20	T7
IO223PB6F20	T6

FG896	
AX1000 Function	Pin Number
IO224NB6F20	R2
IO224PB6F20	T2
Bank 7	
IO225NB7F21	R7
IO225PB7F21	R6
IO226NB7F21	R4
IO226PB7F21	R5
IO227NB7F21	R8
IO227PB7F21	R9
IO228NB7F21	P1
IO228PB7F21	R1
IO229NB7F21	P9
IO229PB7F21	P8
IO230NB7F21	N2
IO230PB7F21	P2
IO231NB7F21	P7
IO231PB7F21	P6
IO232NB7F21	N3
IO232PB7F21	P3
IO233NB7F21	P4
IO233PB7F21	P5
IO234NB7F21	L1
IO234PB7F21	M1
IO235NB7F21	M4
IO235PB7F21	N4
IO236NB7F22	N7
IO236PB7F22	N6
IO237NB7F22	N8
IO237PB7F22	N9
IO238NB7F22	M5
IO238PB7F22	N5
IO239NB7F22	L2
IO239PB7F22	M2
IO240NB7F22	L3
IO240PB7F22	M3

FG896	
AX1000 Function	Pin Number
IO241NB7F22	M8
IO241PB7F22	M7
IO242NB7F22	K4
IO242PB7F22	L4
IO243NB7F22	L6
IO243PB7F22	M6
IO244NB7F22	K5
IO244PB7F22	L5
IO245NB7F22	J4
IO245PB7F22	J3
IO246NB7F22	G2
IO246PB7F22	H2
IO247NB7F23	L8
IO247PB7F23	L7
IO248NB7F23	G3
IO248PB7F23	H3
IO249NB7F23	G4
IO249PB7F23	H4
IO250NB7F23	J6
IO250PB7F23	K6
IO251NB7F23	H5
IO251PB7F23	J5
IO252NB7F23	F2
IO252PB7F23	F1
IO253NB7F23	K8
IO253PB7F23	K7
IO254NB7F23	F4
IO254PB7F23	F3
IO255NB7F23	G6
IO255PB7F23	H6
IO256NB7F23	F5
IO256PB7F23	G5
IO257NB7F23	H7
IO257PB7F23	J7
Dedicated I/O	

PQ208	
AX500 Function	Pin Number
Bank 0	
IO03NB0F0	198
IO03PB0F0	199
IO04NB0F0	197
IO19NB0F1/HCLKAN	191
IO19PB0F1/HCLKAP	192
IO20NB0F1/HCLKBN	185
IO20PB0F1/HCLKBP	186
Bank 1	
IO21NB1F2/HCLKCN	180
IO21PB1F2/HCLKCP	181
IO22NB1F2/HCLKDN	174
IO22PB1F2/HCLKDP	175
IO23NB1F2	170
IO23PB1F2	171
IO37NB1F3	165
IO37PB1F3	166
IO39NB1F3	161
IO39PB1F3	162
IO41NB1F3	159
IO41PB1F3	160
Bank 2	
IO43NB2F4	151
IO43PB2F4	153
IO44NB2F4	152
IO44PB2F4	154
IO45PB2F4	148
IO46NB2F4	146
IO46PB2F4	147
IO48NB2F4	144
IO48PB2F4	145
IO57NB2F5	139
IO57PB2F5	140
IO58PB2F5	141
IO59NB2F5	137
IO59PB2F5	138
IO61NB2F5	132

PQ208	
AX500 Function	Pin Number
IO61PB2F5	134
IO62NB2F5	131
IO62PB2F5	133
Bank 3	
IO63NB3F6	127
IO63PB3F6	129
IO64NB3F6	126
IO64PB3F6	128
IO66NB3F6	122
IO66PB3F6	123
IO68NB3F6	120
IO68PB3F6	121
IO77NB3F7	116
IO77PB3F7	117
IO79NB3F7	114
IO79PB3F7	115
IO81NB3F7	110
IO81PB3F7	111
IO82NB3F7	108
IO82PB3F7	109
IO83NB3F7	106
IO83PB3F7	107
Bank 4	
IO84PB4F8	103
IO85NB4F8	100
IO86NB4F8	101
IO86PB4F8	102
IO87NB4F8	96
IO87PB4F8	97
IO101NB4F9	91
IO101PB4F9	92
IO103NB4F9/CLKEN	87
IO103PB4F9/CLKEP	88
IO104NB4F9/CLKFN	81
IO104PB4F9/CLKFP	82
Bank 5	
IO105NB5F10/CLKGN	76

PQ208	
AX500 Function	Pin Number
IO105PB5F10/CLKGP	77
IO106NB5F10/CLKHN	70
IO106PB5F10/CLKHP	71
IO107NB5F10	66
IO107PB5F10	67
IO119NB5F11	62
IO121NB5F11	60
IO121PB5F11	61
IO123NB5F11	56
IO123PB5F11	57
IO125NB5F11	54
IO125PB5F11	55
Bank 6	
IO127NB6F12	47
IO127PB6F12	49
IO128NB6F12	48
IO128PB6F12	50
IO129NB6F12	42
IO129PB6F12	43
IO130PB6F12	44
IO132NB6F12	40
IO132PB6F12	41
IO141NB6F13	35
IO141PB6F13	36
IO142PB6F13	37
IO143NB6F13	33
IO143PB6F13	34
IO145NB6F13	28
IO145PB6F13	30
IO146NB6F13	27
IO146PB6F13	29
Bank 7	
IO147NB7F14	23
IO147PB7F14	25
IO148NB7F14	22
IO148PB7F14	24
IO150NB7F14	18

CG624	
AX2000 Function	Pin Number
IO310NB7F29	N10
IO310PB7F29	N9
IO311NB7F29	K1
IO311PB7F29	L1
IO313NB7F29	M5
IO316NB7F29	L6
IO316PB7F29	L5
IO317NB7F29	K2
IO317PB7F29	L2
IO318NB7F29	K4
IO318PB7F29	L4
IO320NB7F29	J3
IO321NB7F30	J2
IO321PB7F30	J1
IO323NB7F30	L7
IO323PB7F30	M7
IO324NB7F30	M9
IO324PB7F30	M8
IO327NB7F30	F1
IO327PB7F30	G1
IO328NB7F30	K7
IO328PB7F30	K6
IO329NB7F30	D1
IO329PB7F30	E1
IO331PB7F30	G2
IO332NB7F31	H3
IO332PB7F31	H2
IO333NB7F31	E2
IO333PB7F31	F2
IO334NB7F31	H4
IO334PB7F31	J4
IO335NB7F31	H5

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
IO335PB7F31	H6
IO337NB7F31	D2
IO338NB7F31	J6
IO338PB7F31	J5
IO339NB7F31	F3
IO339PB7F31	E3
IO340NB7F31	G4*
IO340PB7F31	G3*
IO341NB7F31	K8
IO341PB7F31	L8
Dedicated I/O	
GND	K5
GND	A18
GND	A2
GND	A24
GND	A25
GND	A8
GND	AA10
GND	AA16
GND	AA18
GND	AA21
GND	AA5
GND	AB22
GND	AB4
GND	AC10
GND	AC16
GND	AC23
GND	AC3
GND	AD1
GND	AD2
GND	AD24
GND	AD25

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
GND	AE1
GND	AE18
GND	AE2
GND	AE24
GND	AE25
GND	AE8
GND	B1
GND	B2
GND	B24
GND	B25
GND	C10
GND	C16
GND	C23
GND	C3
GND	D22
GND	D4
GND	E10
GND	E16
GND	E21
GND	E5
GND	E8
GND	H1
GND	H21
GND	H25
GND	K21
GND	K23
GND	K3
GND	L11
GND	L12
GND	L13
GND	L14
GND	L15

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

Datasheet Categories

Categories

In order to provide the latest information to designers, some datasheet parameters are published before data has been fully characterized from silicon devices. The data provided for a given device, as highlighted in the "Axcelerator Family Device Status" table on page iii, is designated as either "Product Brief," "Advance," "Preliminary," or "Production." The definitions of these categories are as follows:

Product Brief

The product brief is a summarized version of a datasheet (advance or production) and contains general product information. This document gives an overview of specific device and family information.

Advance

This version contains initial estimated information based on simulation, other products, devices, or speed grades. This information can be used as estimates, but not for production. This label only applies to the DC and Switching Characteristics chapter of the datasheet and will only be used when the data has not been fully characterized.

Preliminary

The datasheet contains information based on simulation and/or initial characterization. The information is believed to be correct, but changes are possible.

Production

This version contains information that is considered to be final.

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